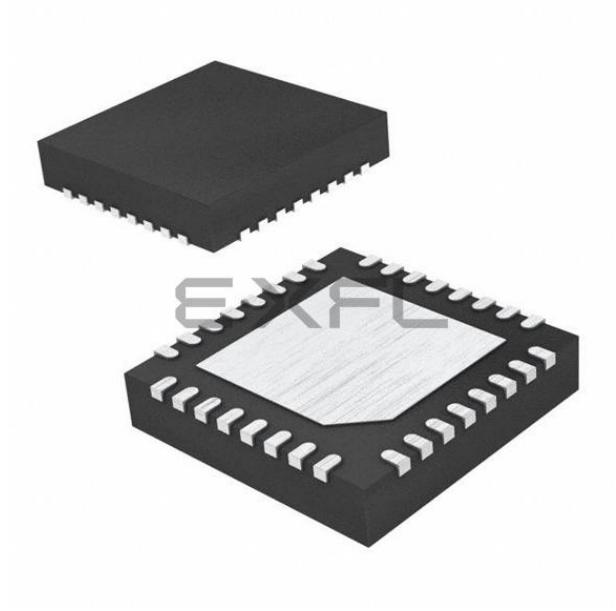
Microchip Technology - DSPIC33EV256GM002-I/MM Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

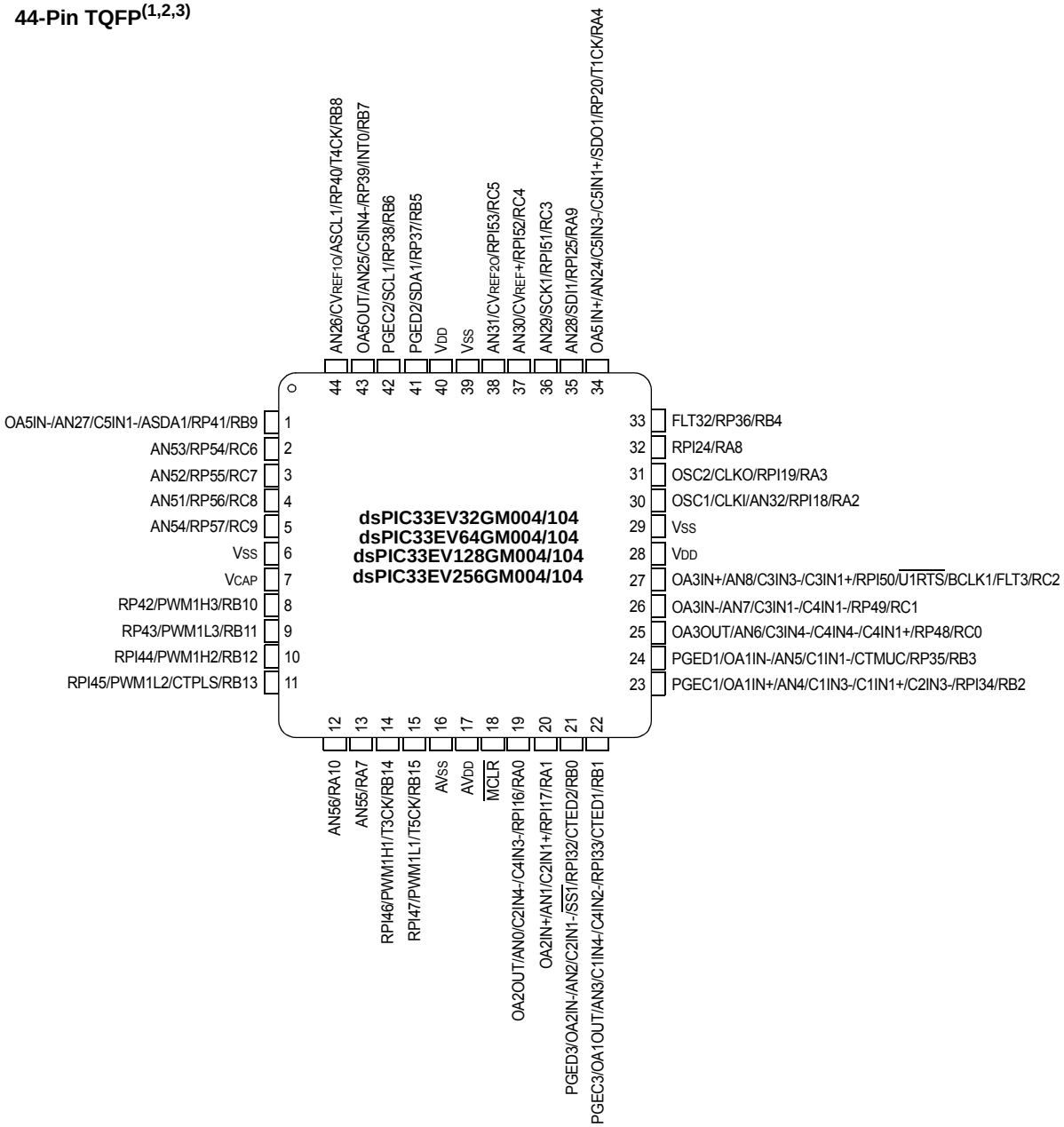
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 11x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev256gm002-i-mm

Pin Diagrams (Continued)

44-Pin TQFP(1,2,3)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.5 "Peripheral Pin Select (PPS)"** for available peripherals and information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: If the op amp is selected when OPAEN (CMxCON<10>) = 1, the OAx input is used; otherwise, the ANx input is used.

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

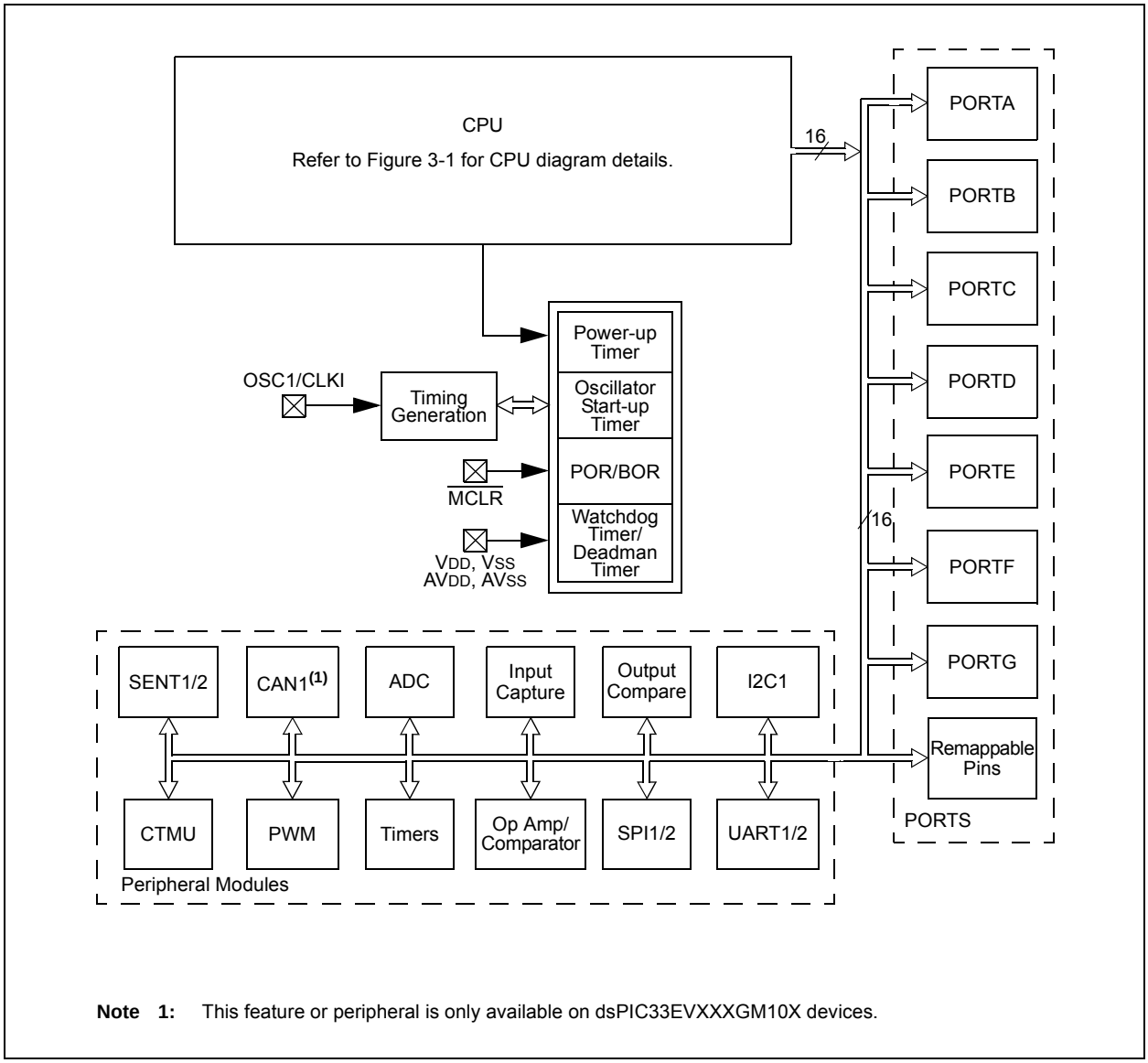
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33EVXXXGM00X/10X family Digital Signal Controller (DSC) devices.

dsPIC33EVXXXGM00X/10X family devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit MCU architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33EVXXXGM00X/10X FAMILY BLOCK DIAGRAM



Note 1: This feature or peripheral is only available on dsPIC33EVXXXGM10X devices.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EVXXXGM00X/10X family of 16-bit microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used)
  (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

Note: The AVDD and AVSS pins must be connected, regardless of the ADC voltage reference source.

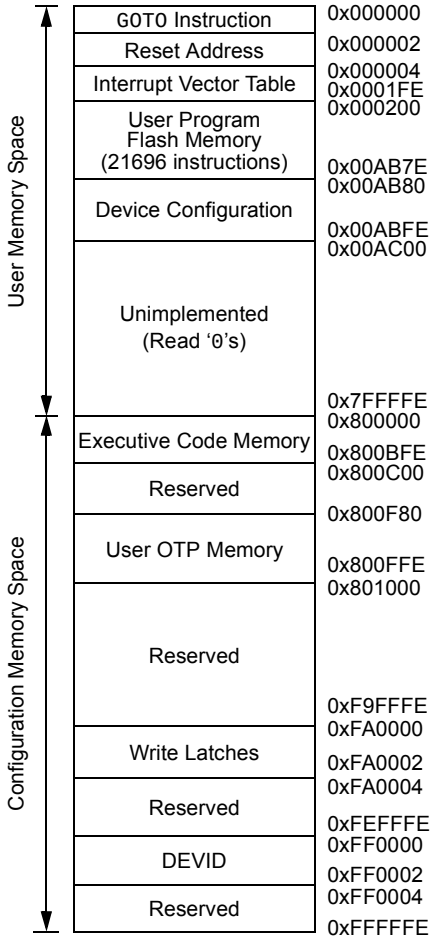
2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10V-20V is recommended. This capacitor should be a Low Equivalent Series Resistance (low-ESR), and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the Printed Circuit Board (PCB):** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing the PCB track inductance.

FIGURE 4-2: PROGRAM MEMORY MAP FOR dsPIC33EV64GM00X/10X DEVICES(1)



Note 1: Memory areas are not shown to scale.

4.3.4 SOFTWARE STACK

The W15 register serves as a dedicated Software Stack Pointer (SSP) and is automatically modified by exception processing, subroutine calls and returns; however, W15 can be referenced by any instruction in the same manner as all other W registers. This simplifies reading, writing and manipulating the SSP (for example, creating stack frames).

Note:	To protect against misaligned stack accesses, W15<0> is fixed to '0' by the hardware.

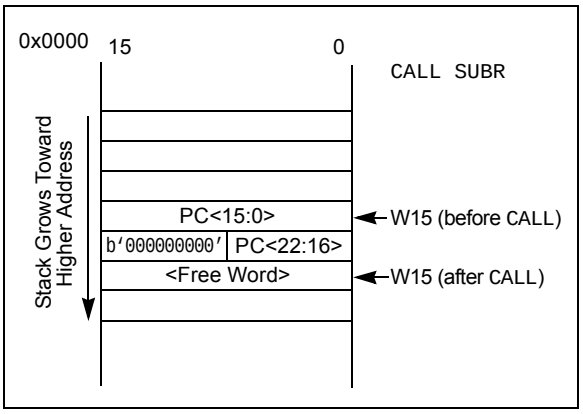
W15 is initialized to 0x1000 during all Resets. This address ensures that the SSP points to valid RAM in all dsPIC33EVXXXGM00X/10X family devices and permits stack availability for non-maskable trap exceptions. These can occur before the SSP is initialized by the user software. You can reprogram the SSP during initialization to any location within the Data Space.

The SSP always points to the first available free word and fills the software stack, working from lower toward higher addresses. Figure 4-14 illustrates how it pre-decrements for a stack pop (read) and post-increments for a stack push (writes).

When the PC is pushed onto the stack, PC<15:0> are pushed onto the first available stack word, then PC<22:16> are pushed into the second available stack location. For a PC push during any CALL instruction, the MSB of the PC is zero-extended before the push, as shown in Figure 4-14. During exception processing, the MSB of the PC is concatenated with the lower 8 bits of the CPU STATUS Register (SR). This allows the contents of SRL to be preserved automatically during interrupt processing.

Note 1:	To maintain system SSP (W15) coherency, W15 is never subject to (EDS) paging, and is therefore, restricted to an address range of 0x0000 to 0xFFFF. The same applies to the W14 when used as a Stack Frame Pointer (SFA = 1).
2:	As the stack can be placed in, and can access X and Y spaces, care must be taken regarding its use, particularly with regard to local automatic variables in a 'C' development environment.

FIGURE 4-14: CALL STACK FRAME



4.4 Instruction Addressing Modes

The addressing modes shown in Table 4-45 form the basis of the addressing modes optimized to support the specific features of the individual instructions. The addressing modes provided in the MAC class of instructions differ from those in the other instruction types.

4.4.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a Working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the MUL instruction), which writes the result to a register or register pair. The MOV instruction allows additional flexibility and can access the entire Data Space.

4.4.2 MCU INSTRUCTIONS

The three-operand MCU instructions are of the form:

```
Operand 3 = Operand 1 <function> Operand 2
```

where, Operand 1 is always a Working register (that is, the addressing mode can only be Register Direct), which is referred to as Wb. Operand 2 can be a W register fetched from data memory or a 5-bit literal. The result location can be either a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-Bit or 10-Bit Literal

Note:	Not all instructions support all of the addressing modes given above. Individual instructions can support different subsets of these addressing modes.

FIGURE 4-16: BIT-REVERSED ADDRESSING EXAMPLE

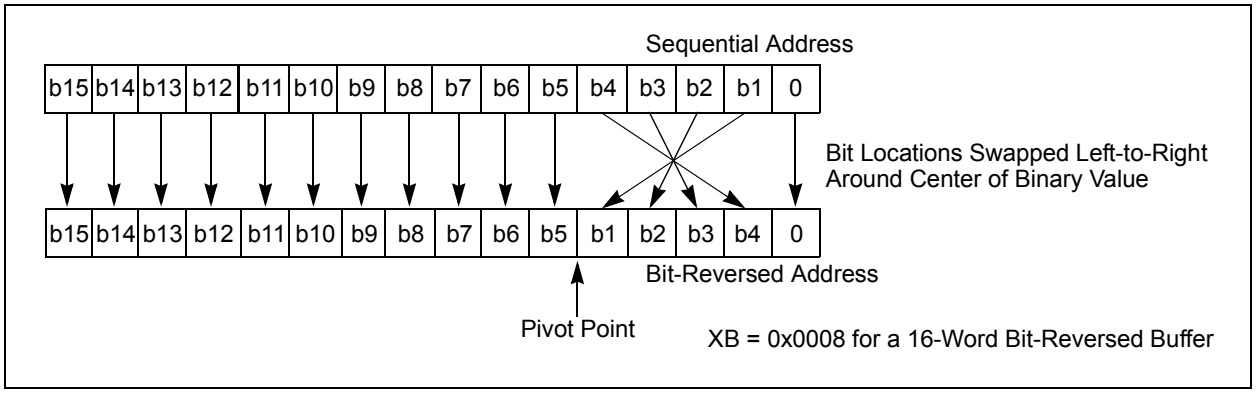


TABLE 4-46: BIT-REVERSED ADDRESSING SEQUENCE (16-ENTRY)

Normal Address					Bit-Reversed Address				
A3	**A2**	**A1**	**A0**	**Decimal**	**A3**	**A2**	**A1**	**A0**	**Decimal**
0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1	0	0	0	8
0	0	1	0	2	0	1	0	0	4
0	0	1	1	3	1	1	0	0	12
0	1	0	0	4	0	0	1	0	2
0	1	0	1	5	1	0	1	0	10
0	1	1	0	6	0	1	1	0	6
0	1	1	1	7	1	1	1	0	14
1	0	0	0	8	0	0	0	1	1
1	0	0	1	9	1	0	0	1	9
1	0	1	0	10	0	1	0	1	5
1	0	1	1	11	1	1	0	1	13
1	1	0	0	12	0	0	1	1	3
1	1	0	1	13	1	0	1	1	11
1	1	1	0	14	0	1	1	1	7
1	1	1	1	15	1	1	1	1	15

REGISTER 10-7: PMD8: PERIPHERAL MODULE DISABLE CONTROL REGISTER 8

U-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	R/W-0
—	—	—	SENT2MD	SENT1MD	—	—	DMTMD
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **SENT2MD:** SENT2 Module Disable bit
1 = SENT2 module is disabled
0 = SENT2 module is enabled

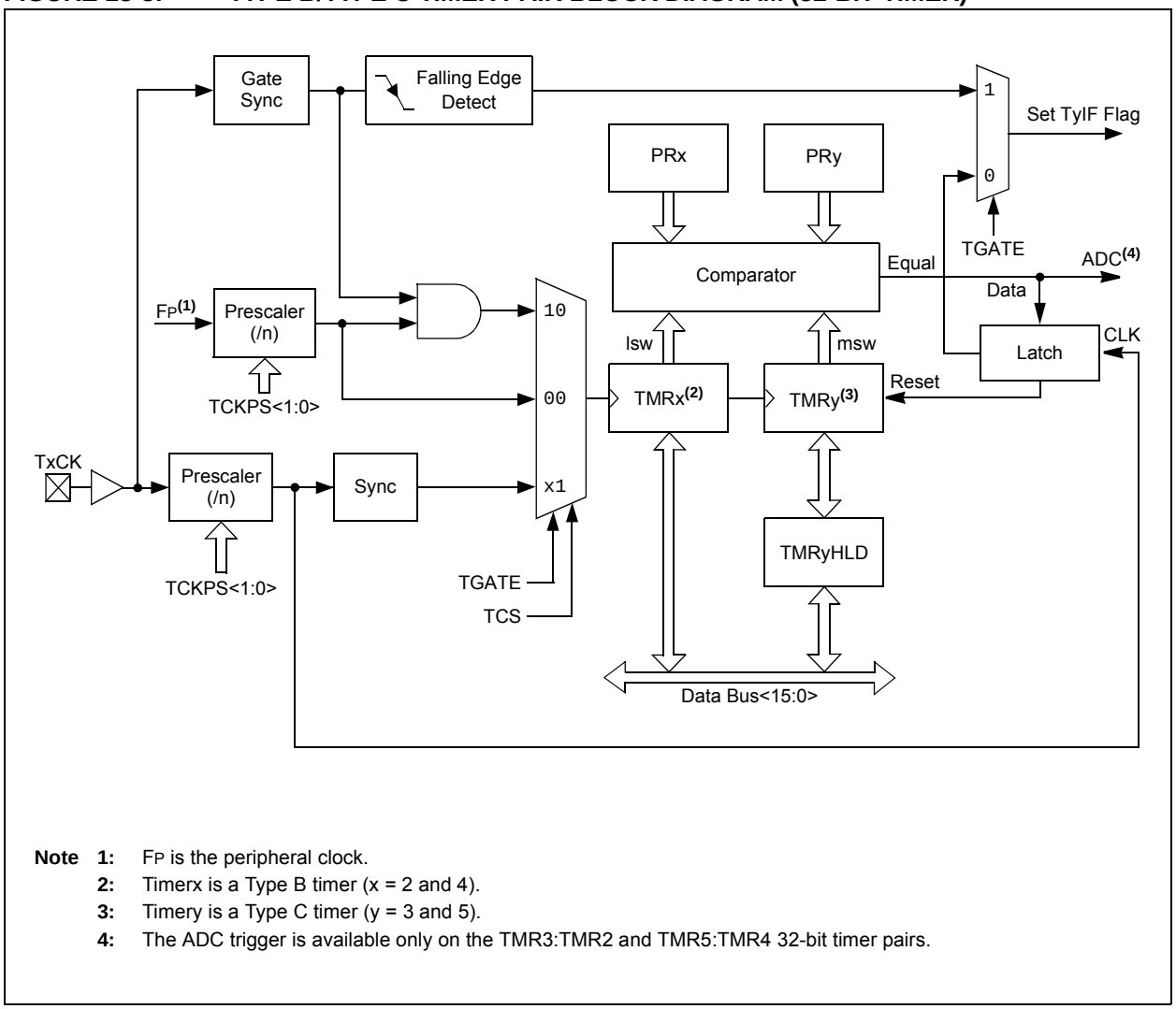
bit 11 **SENT1MD:** SENT1 Module Disable bit
1 = SENT1 module is disabled
0 = SENT1 module is enabled

bit 10-9 **Unimplemented:** Read as ‘0’

bit 8 **DMTMD:** Deadman Timer Disable bit
1 = Deadman Timer is disabled
0 = Deadman Timer is enabled

bit 7-0 **Unimplemented:** Read as ‘0’

FIGURE 13-3: TYPE B/TYPE C TIMER PAIR BLOCK DIAGRAM (32-BIT TIMER)



Note 1: FP is the peripheral clock.
2: Timerx is a Type B timer (x = 2 and 4).
3: Timery is a Type C timer (y = 3 and 5).
4: The ADC trigger is available only on the TMR3:TMR2 and TMR5:TMR4 32-bit timer pairs.

REGISTER 14-3: DMTCLR: DEADMAN TIMER CLEAR REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STEP2<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-0 **STEP2<7:0>:** DMT Clear Timer bits

00001000 = Clears STEP1<7:0>, STEP2<7:0> and the Deadman Timer if preceded by the correct loading of the STEP1<7:0> bits in the correct sequence. The write to these bits may be verified by reading the DMTCNTL/H register and observing the counter being reset.

All Other Write Patterns = Sets the BAD2 bit; the value of STEP1<7:0> will remain unchanged and the new value being written to STEP2<7:0> will be captured. These bits are cleared when a DMT Reset event occurs.

22.3 CAN Control Registers

REGISTER 22-1: CxCTRL1: CANx CONTROL REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0
—	—	CSIDL	ABAT	CANCKS	REQOP2	REQOP1	REQOP0
bit 15							bit 8

R-1	R-0	R-0	U-0	R/W-0	U-0	U-0	R/W-0
OPMODE2	OPMODE1	OPMODE0	—	CANCAP	—	—	WIN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **CSIDL:** CANx Stop in Idle Mode bit
1 = Discontinues module operation when the device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **ABAT:** Abort All Pending Transmissions bit
1 = Signals all transmit buffers to abort transmission
0 = Module will clear this bit when all transmissions are aborted

bit 11 **CANCKS:** CANx Module Clock (FCAN) Source Select bit
1 = FCAN is equal to 2 * FP
0 = FCAN is equal to FP

bit 10-8 **REQOP<2:0>:** Request Operation Mode bits
111 = Sets Listen All Messages mode
110 = Reserved
101 = Reserved
100 = Sets Configuration mode
011 = Sets Listen Only mode
010 = Sets Loopback mode
001 = Sets Disable mode
000 = Sets Normal Operation mode

bit 7-5 **OPMODE<2:0>**: Operation Mode bits
111 = Module is in Listen All Messages mode
110 = Reserved
101 = Reserved
100 = Module is in Configuration mode
011 = Module is in Listen Only mode
010 = Module is in Loopback mode
001 = Module is in Disable mode
000 = Module is in Normal Operation mode

bit 4 **Unimplemented:** Read as '0'

bit 3 **CANCAP:** CANx Message Receive Timer Capture Event Enable bit
1 = Enables input capture based on CAN message receive
0 = Disables CAN capture

bit 2-1 **Unimplemented:** Read as '0'

bit 0 **WIN:** SFR Map Window Select bit
1 = Uses filter window
0 = Uses buffer window

REGISTER 22-8: CxEC: CANx TRANSMIT/RECEIVE ERROR COUNT REGISTER

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
TERRCNT<7:0>							
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
RERRCNT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **TERRCNT<7:0>:** Transmit Error Count bits

bit 7-0 **RERRCNT<7:0>:** Receive Error Count bits

REGISTER 22-9: CxCFG1: CANx BAUD RATE CONFIGURATION REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-6 **SJW<1:0>:** Synchronization Jump Width bits

11 = Length is 4 x T_Q
10 = Length is 3 x T_Q
01 = Length is 2 x T_Q
00 = Length is 1 x T_Q

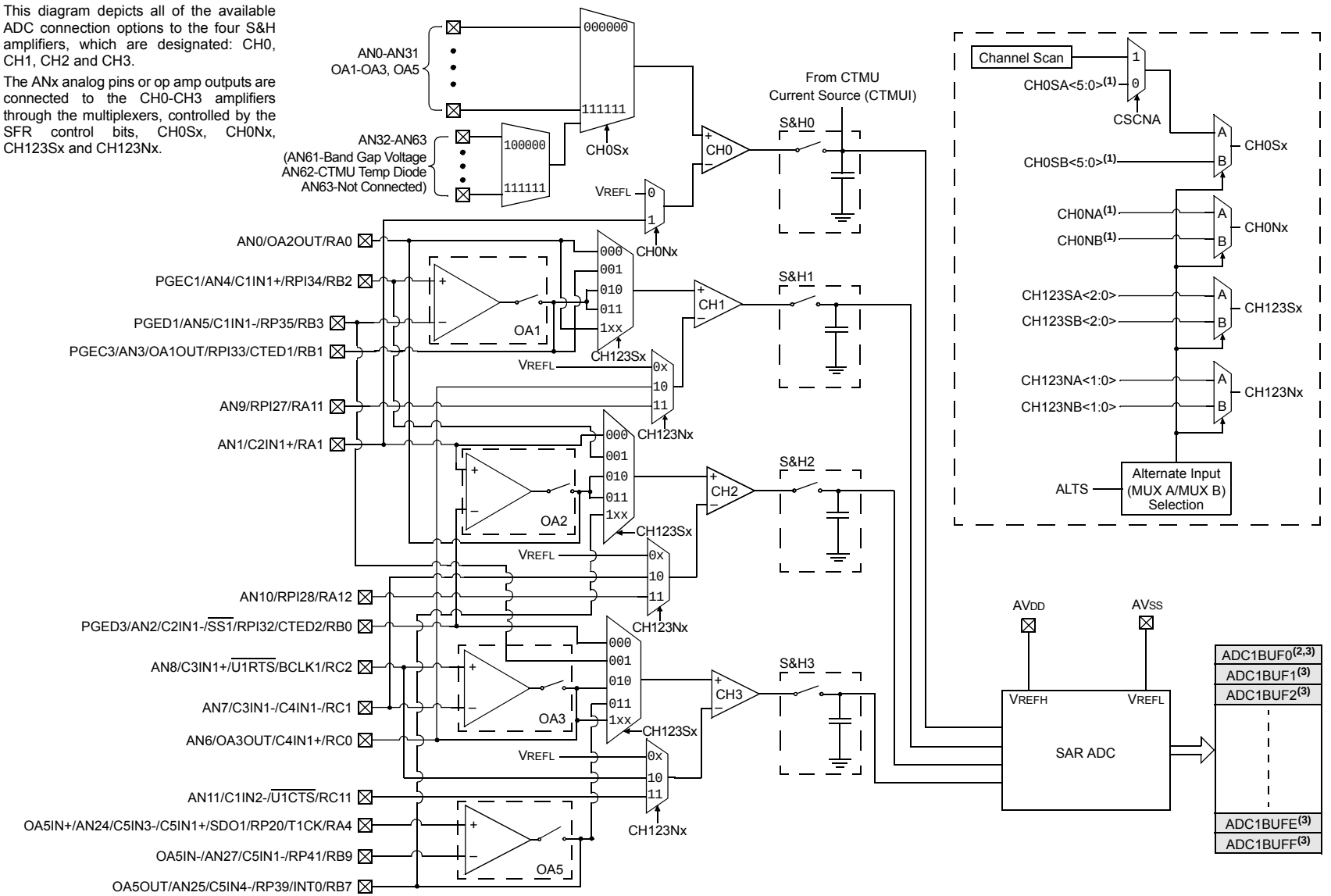
bit 5-0 **BRP<5:0>:** Baud Rate Prescaler bits

11 1111 = T_Q = 2 x 64 x 1/F_{CAN}
•
•
•
00 0010 = T_Q = 2 x 3 x 1/F_{CAN}
00 0001 = T_Q = 2 x 2 x 1/F_{CAN}
00 0000 = T_Q = 2 x 1 x 1/F_{CAN}

FIGURE 24-1: ADCx MODULE BLOCK DIAGRAM WITH CONNECTION OPTIONS FOR ANx PINS AND OP AMPS

This diagram depicts all of the available ADC connection options to the four S&H amplifiers, which are designated: CH0, CH1, CH2 and CH3.

The ANx analog pins or op amp outputs are connected to the CH0-CH3 amplifiers through the multiplexers, controlled by the SFR control bits, CH0Sx, CH0Nx, CH123Sx and CH123Nx.



Note 1: Channels 1, 2 and 3 are not applicable for the 12-bit mode of operation.
2: When ADDMAEN (ADxCON4<8>) = 0, ADC1BUF0-ADC1BUFF are used.
3: When ADDMAEN (ADxCON4<8>) = 1 enabling DMA, only ADC1BUF0 is used.

27.6 In-Circuit Serial Programming

The dsPIC33EVXXXGM00X/10X family devices can be serially programmed while in the end application circuit. This is done with two lines for clock and data, and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to *"dsPIC33EVXXXGM00X/10X Families Flash Programming Specification"* (DS70005137) for details about In-Circuit Serial Programming™ (ICSP™).

Any of the following three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

27.7 In-Circuit Debugger

When MPLAB® ICD 3 or REAL ICE™ is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB X IDE. Debugging functionality is controlled through the PGECx (Emulation/Debug Clock) and PGEDx (Emulation/Debug Data) pin functions.

Any of the following three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{MCLR}$, V_{DD}, V_{SS} and the PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins (PGECx and PGEDx).

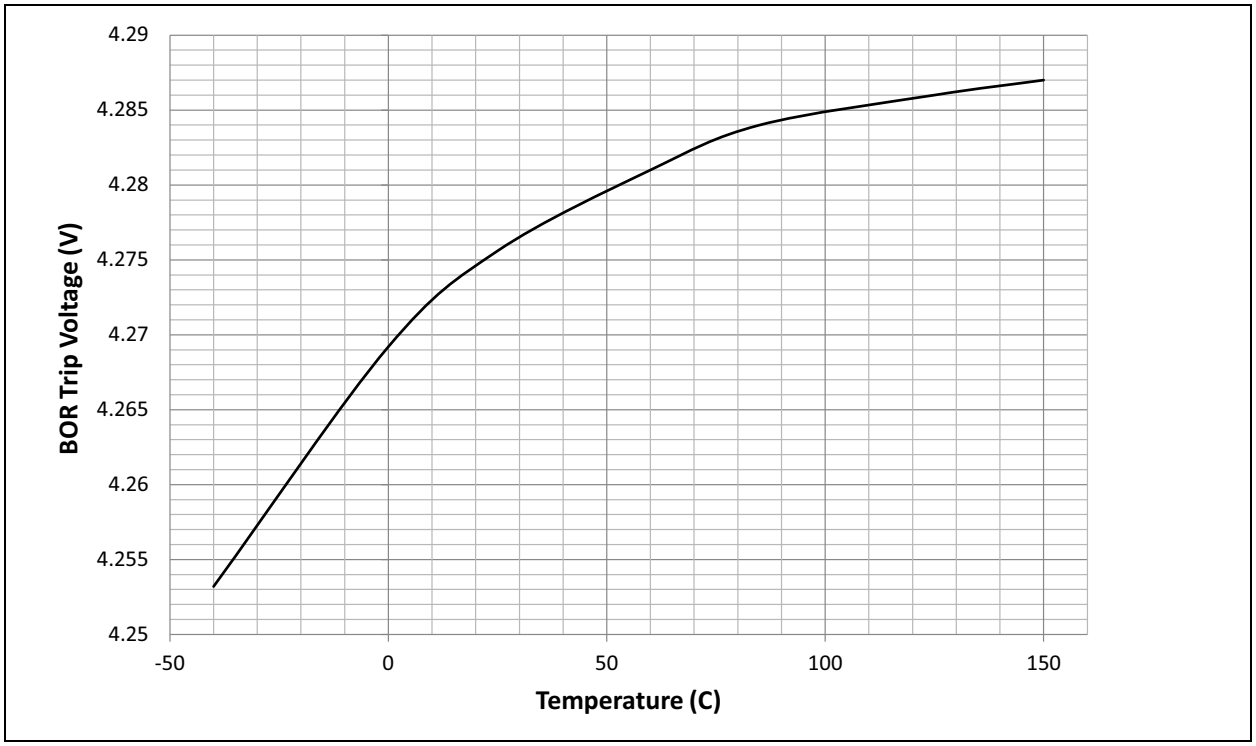
27.8 Code Protection and CodeGuard™ Security

The dsPIC33EVXXXGM00X/10X family devices offer Intermediate CodeGuard Security that supports General Segment (GS) security, Boot Segment (BS) security and Configuration Segment (CS) security. This feature helps protect individual Intellectual Properties.

Note:	Refer to **"CodeGuard™ Intermediate Security"** (DS70005182) in the *"dsPIC33/PIC24 Family Reference Manual"* for further information on usage, configuration and operation of CodeGuard Security.

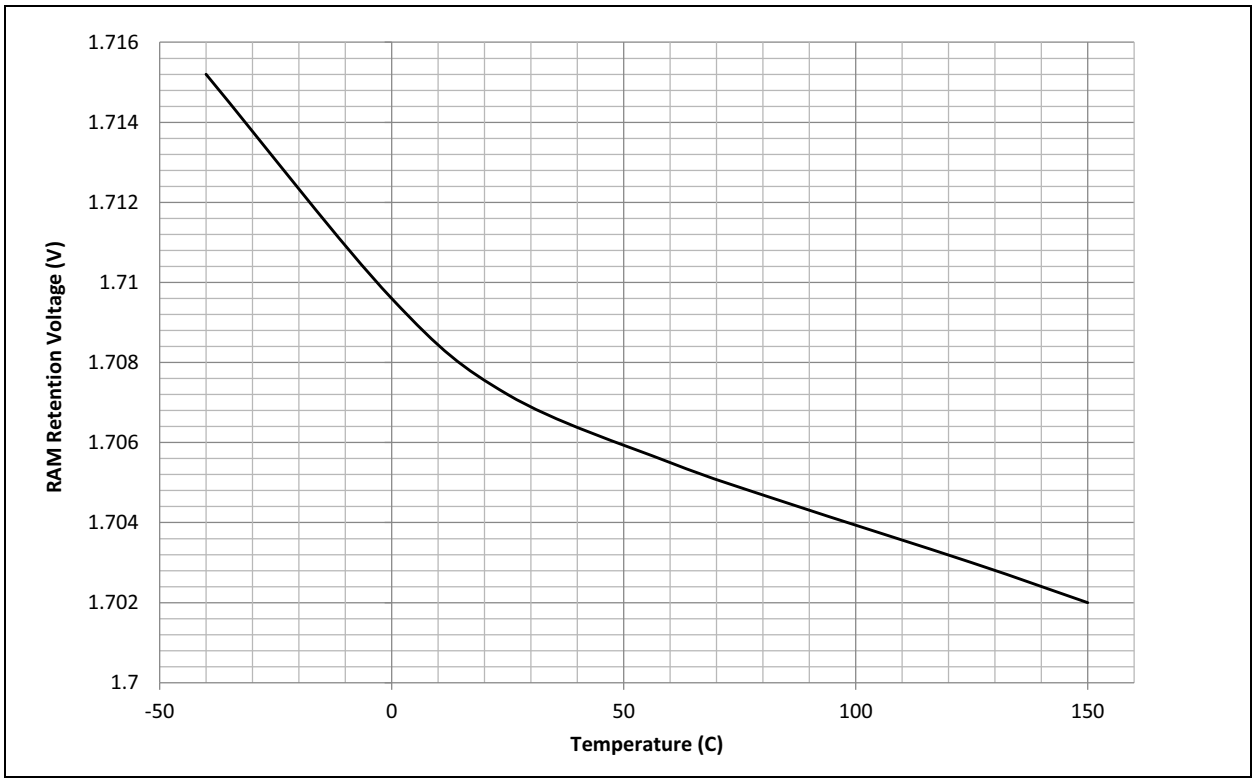
32.12 VBOR

FIGURE 32-35: TYPICAL BOR TRIP RANGE vs. TEMPERATURE



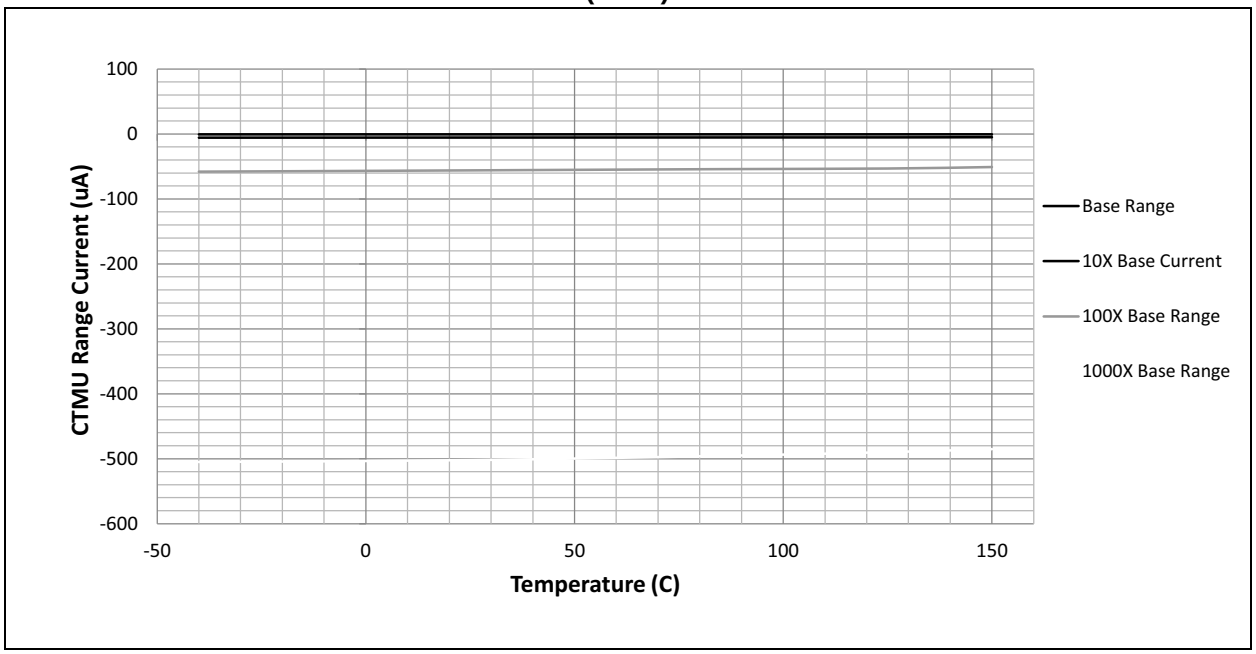
32.13 RAM Retention

FIGURE 32-36: TYPICAL RAM RETENTION VOLTAGE vs. TEMPERATURE



32.15 CTMU Current vs. Temperature

FIGURE 32-39: TYPICAL CTMU CURRENT (IRNG) vs. TEMPERATURE



32.16 CTMU Temperature Forward Diode

FIGURE 32-40: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE vs. TEMPERATURE

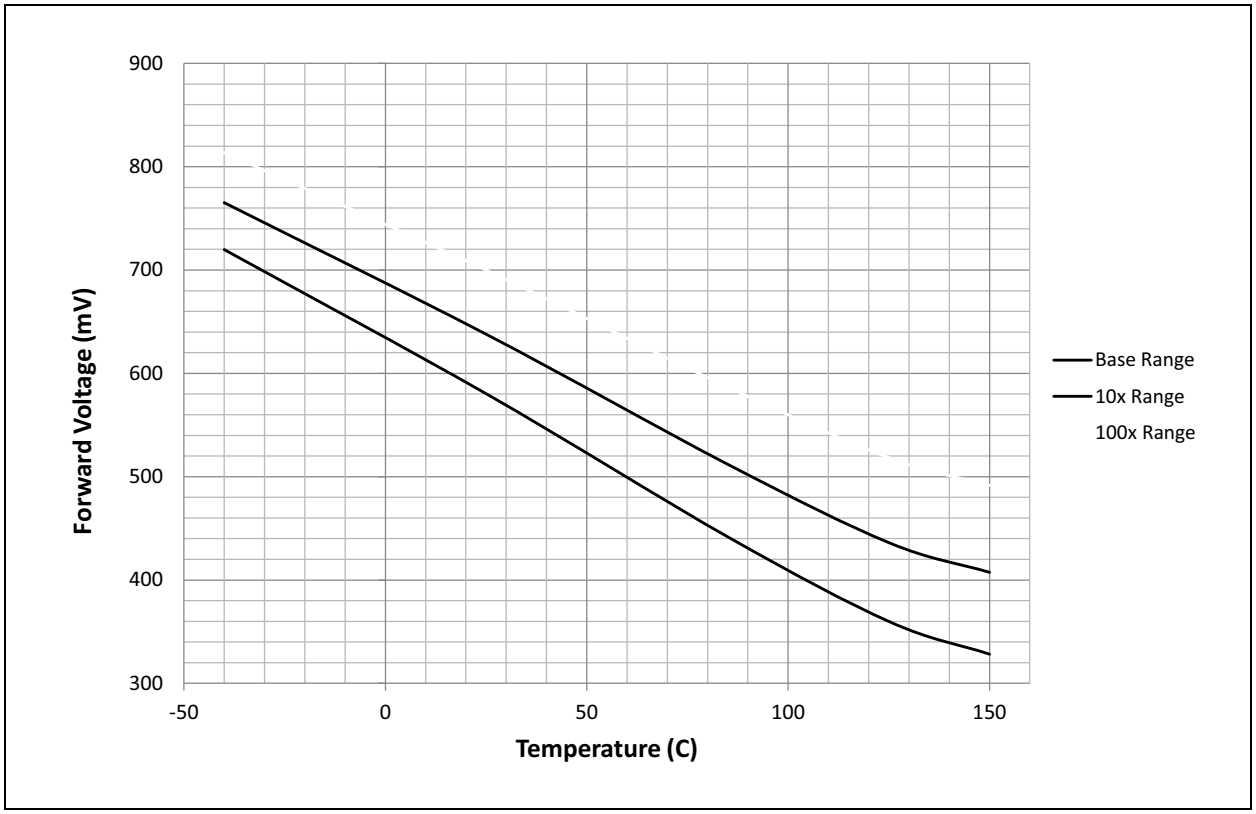


FIGURE 32-47: TYPICAL INL (V_{DD} = 5.5V, +85°C)

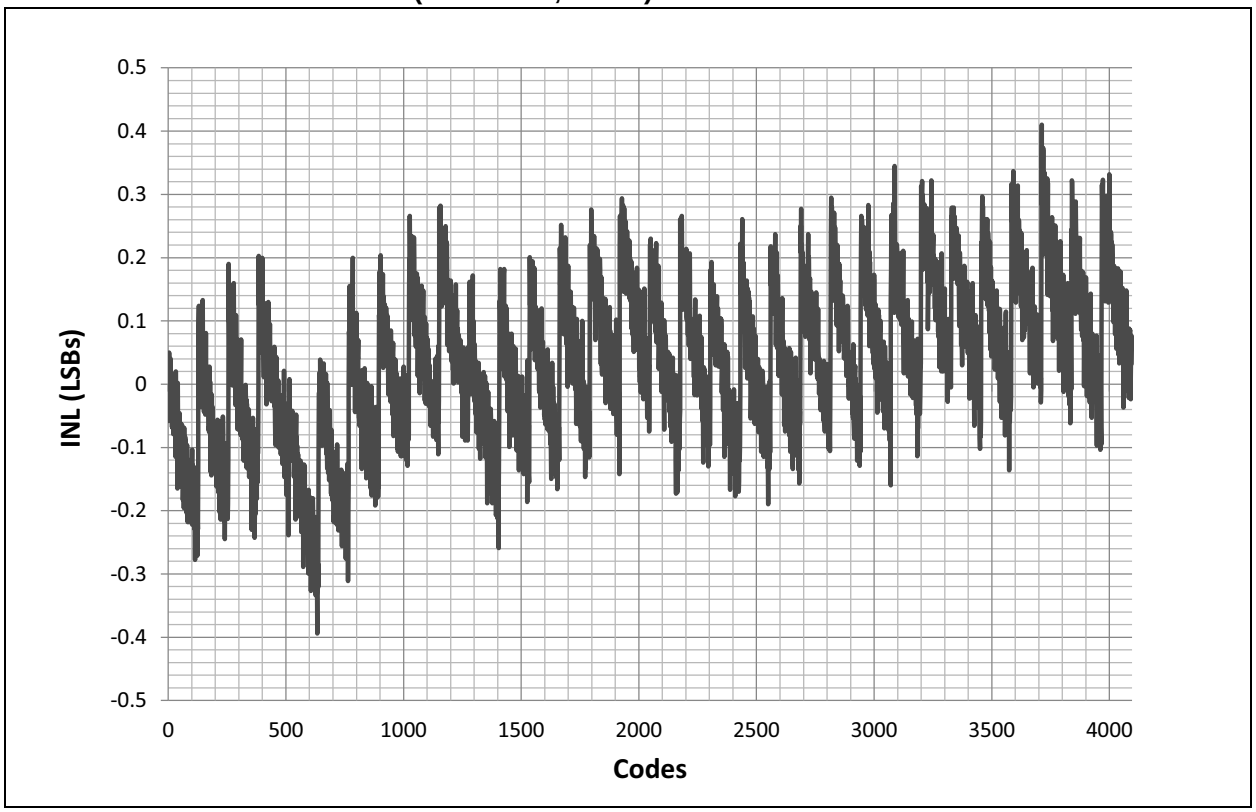


FIGURE 32-48: TYPICAL INL (V_{DD} = 5.5V, +125°C)

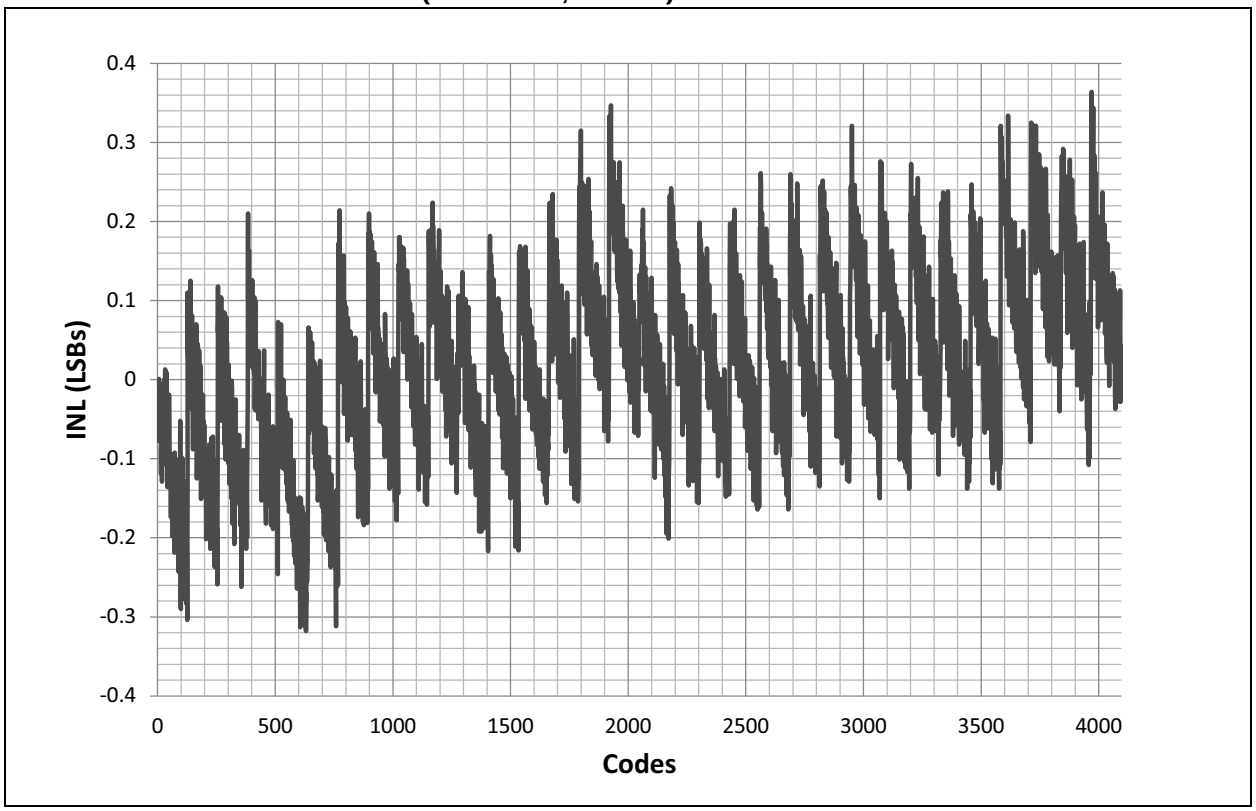


FIGURE 33-3: TYPICAL IDD vs. VDD (EC MODE, 20 MIPS)

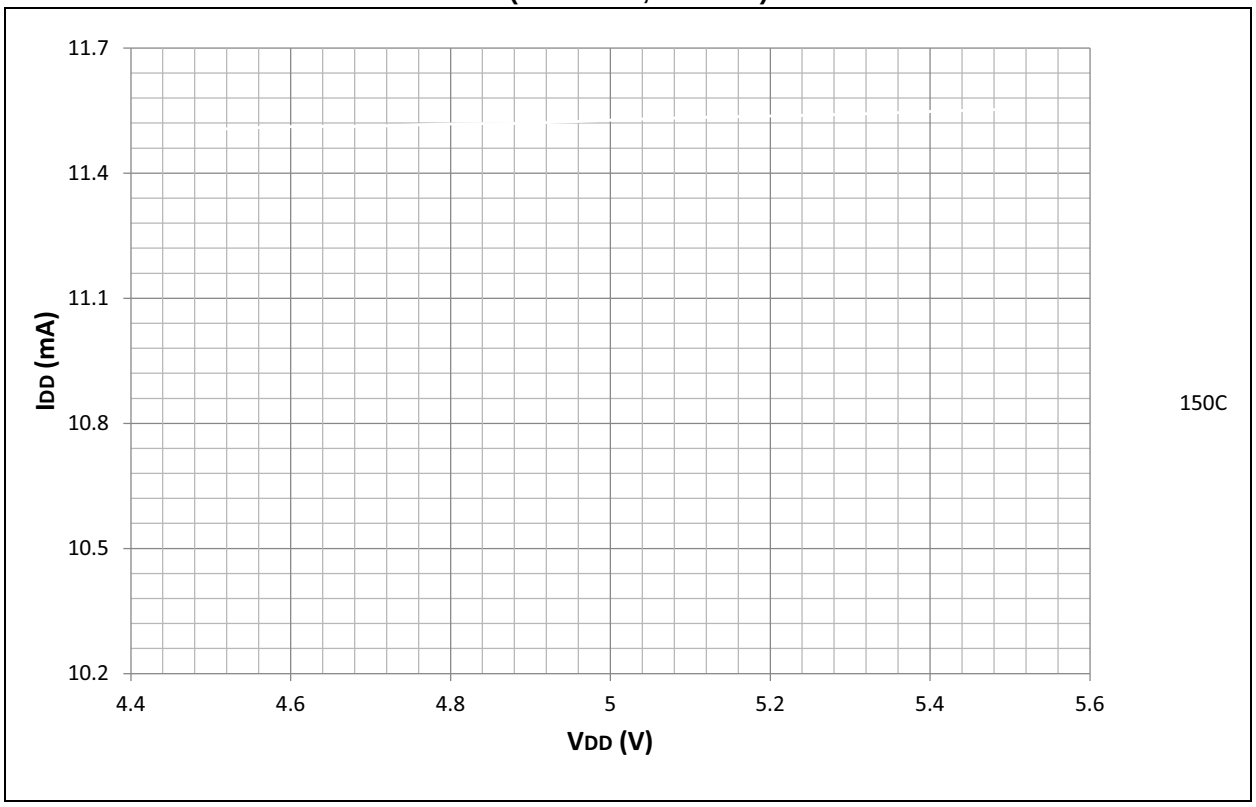
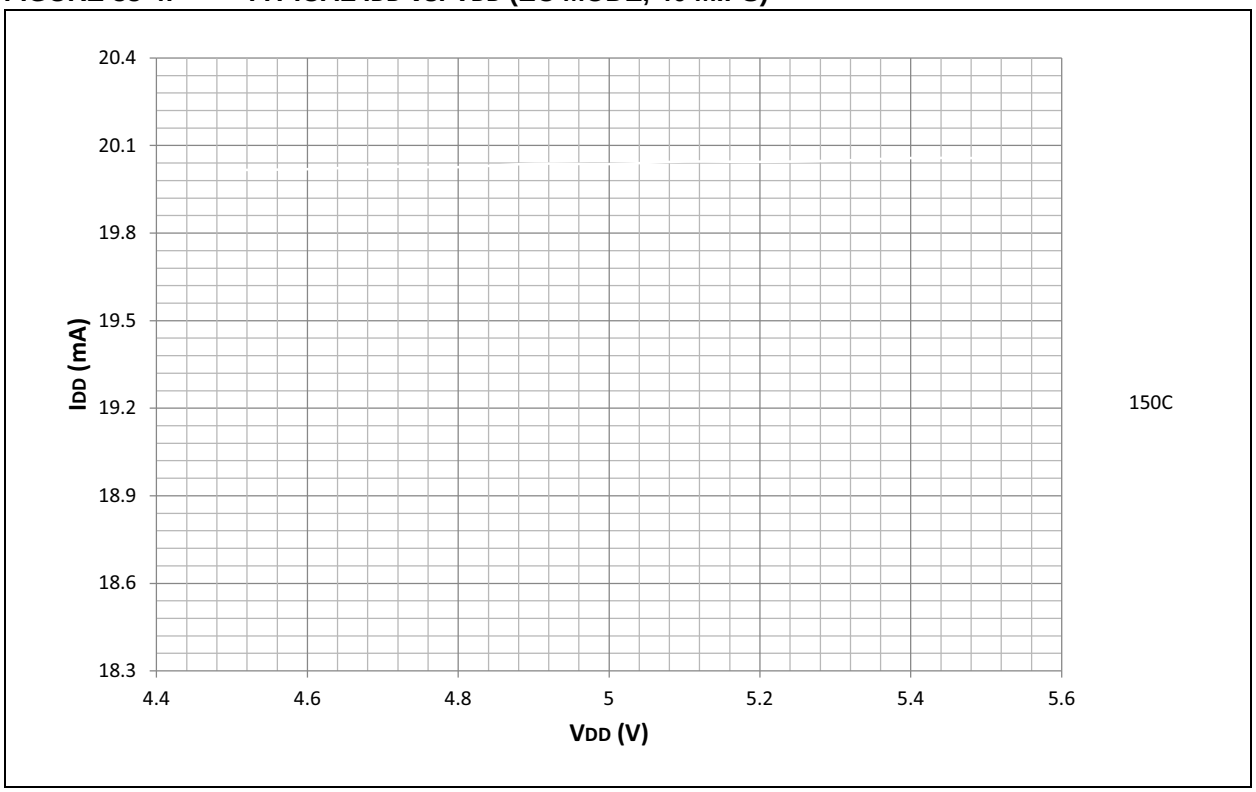


FIGURE 33-4: TYPICAL IDD vs. VDD (EC MODE, 40 MIPS)



33.3 IDOZE

FIGURE 33-9: TYPICAL IDOZE vs. VDD (DOZE 1:2, 70 MIPS)

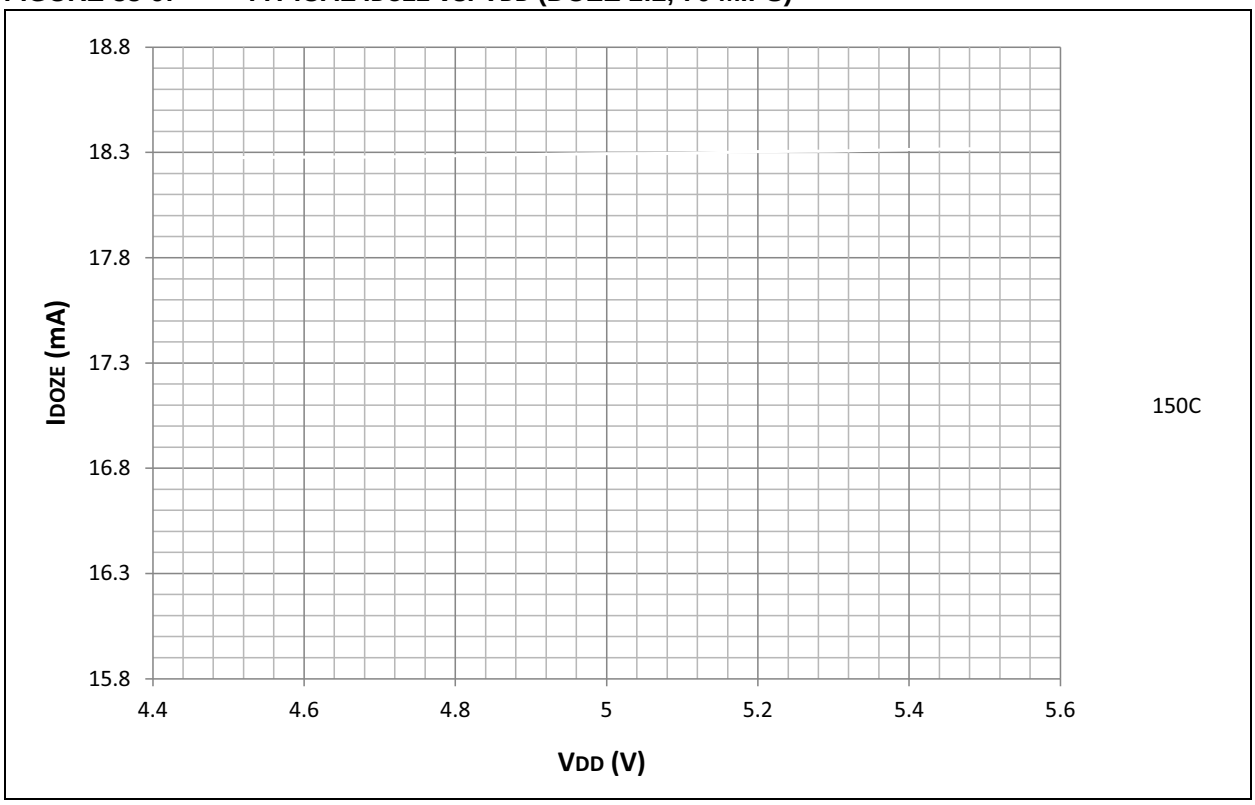


FIGURE 33-10: TYPICAL/MAXIMUM IDOZE vs. TEMPERATURE (DOZE 1:2, 70 MIPS)

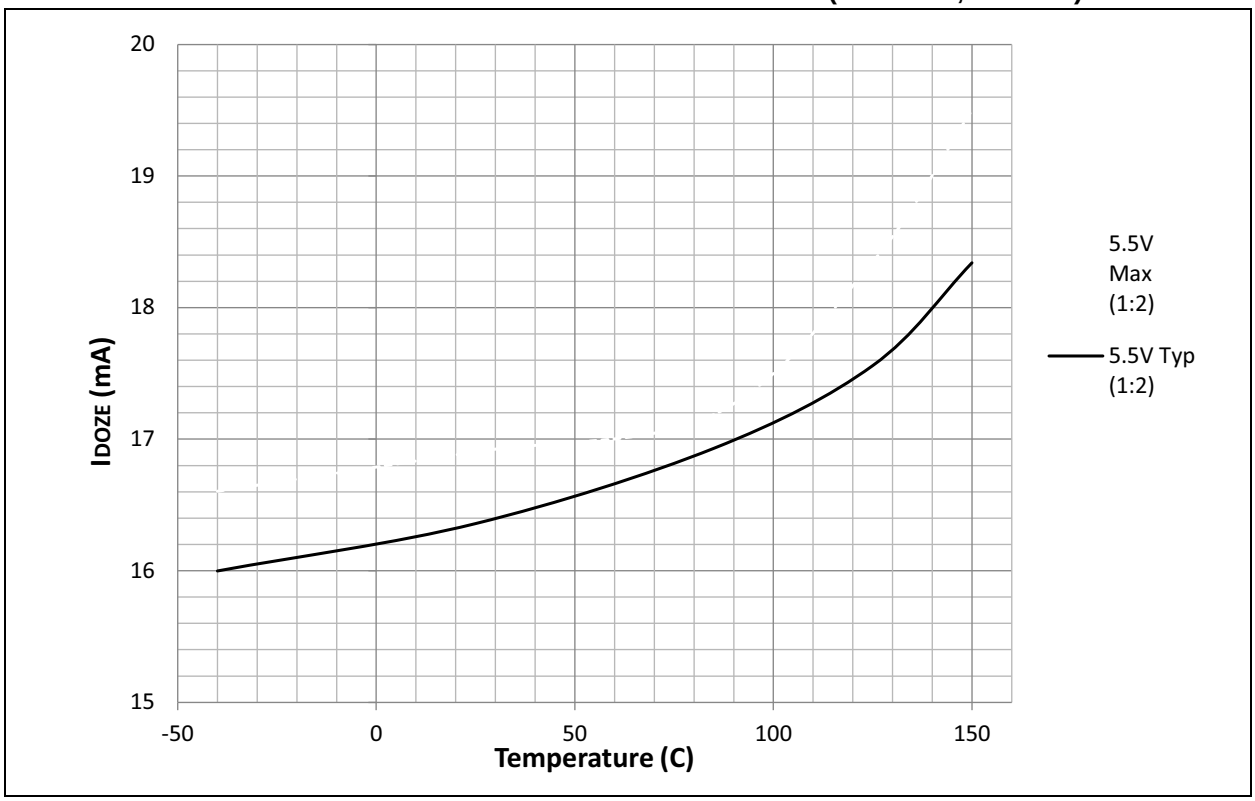


FIGURE 33-27: TYPICAL V_{OH} 4x DRIVER PINS vs. I_{OH} (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)

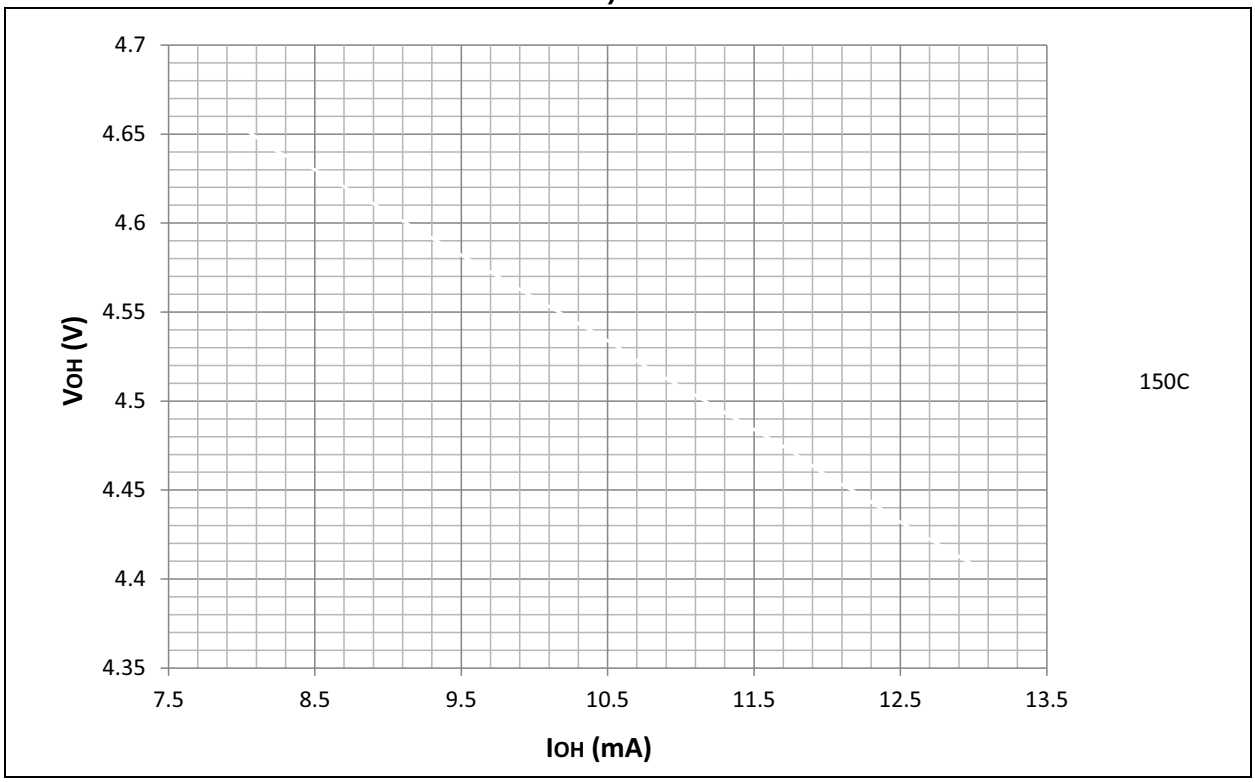
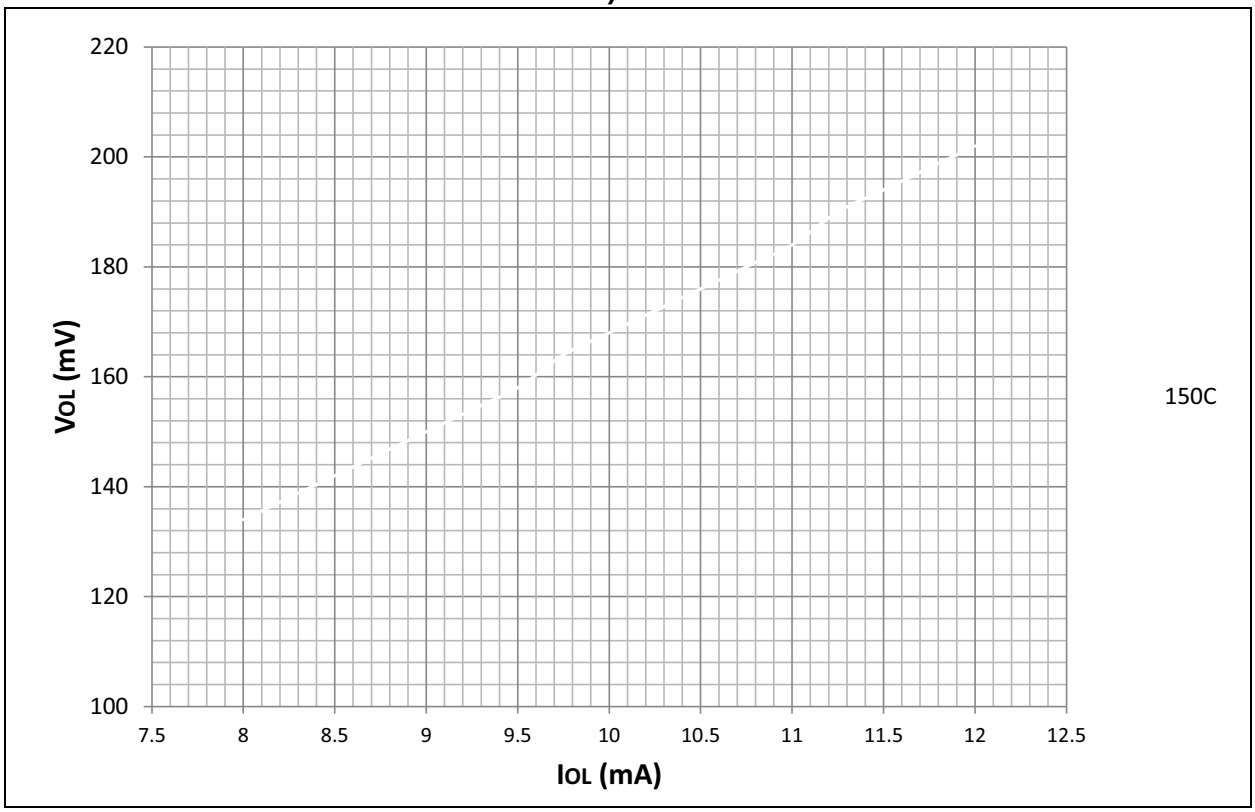
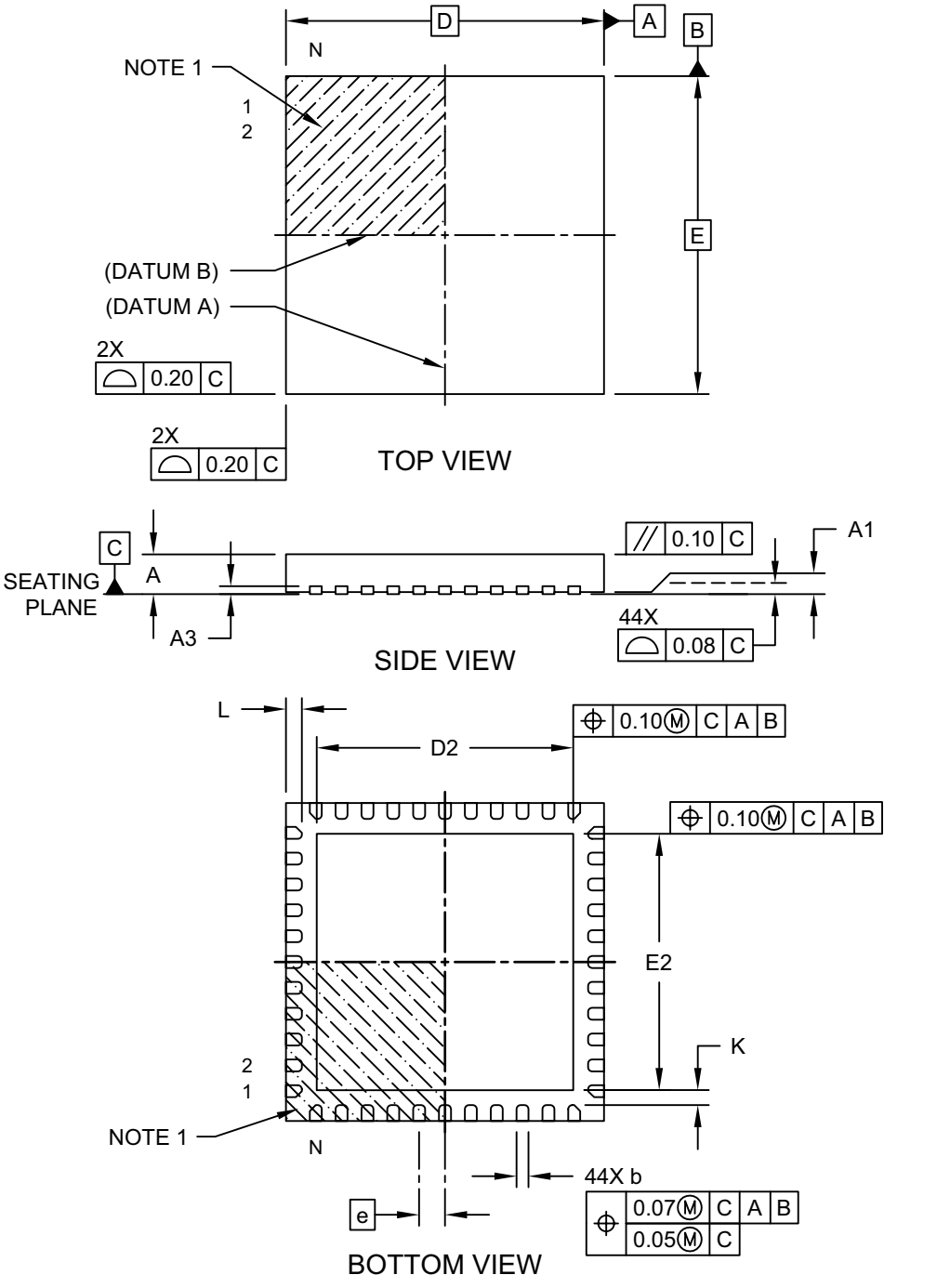


FIGURE 33-28: TYPICAL V_{OL} 8x DRIVER PINS vs. I_{OL} (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-103D Sheet 1 of 2